Title (en)

ELECTRONIC CIRCUIT BOARD INTERMEDIATE MEMBER, MANUFACTURING METHOD THEREFOR, MANUFACTURING EQUIPMENT THEREFOR, METHOD FOR MANUFACTURING NONCONTACT ID CARD AND THE LIKE, AND EQUIPMENT THEREFOR

Title (de)

ZWISCHENGLIED EINER ELEKTRONISCHEN LEITERPLATTE, HERSTELLUNGSVERFAHREN DAFÜR, HERSTELLUNGSGERÄTE DAFÜR, VERFAHREN ZUR HERSTELLUNG EINER KONTAKTLOSEN ID-KARTE UND DERGLEICHEN UND GERÄTE DAFÜR

Title (fr)

ORGANE INTERMEDIAIRE DE CARTE DE CIRCUIT ELECTRONIQUE; PROCEDE DE FABRICATION; EQUIPEMENT DE FABRICATION; PROCEDE DE FABRICATION D UNE CARTE ID SANS CONTACT ET EQUIPEMENT

Publication

EP 1699000 A1 20060906 (EN)

Application

EP 04807674 A 20041224

Priority

- JP 2004019317 W 20041224
- JP 2003433502 A 20031226

Abstract (en)

Adverse affects due to a failure interposer board and a blank section are prevented from occurrence by arranging only conforming interposer boards (1) on a carrier tape (2) at every predetermined interval.

IPC 8 full level

G06K 19/077 (2006.01); **B07C 5/344** (2006.01); **G06K 19/00** (2006.01)

CPC (source: EP KR US)

G06K 17/00 (2013.01 - KR); **G06K 19/00** (2013.01 - KR); **G06K 19/077** (2013.01 - KR); **G06K 19/07718** (2013.01 - EP US); **G06K 19/07749** (2013.01 - EP US); **G06K 19/07752** (2013.01 - EP US)

Designated contracting state (EPC)

DE

DOCDB simple family (publication)

EP 1699000 A1 20060906; **EP 1699000 A4 20090826**; CN 1898681 A 20070117; JP WO2005073902 A1 20080110; KR 20070026346 A 20070308; TW 200525654 A 20050801; US 2007171619 A1 20070726; WO 2005073902 A1 20050811

DOCDB simple family (application)

EP 04807674 A 20041224; CN 200480039086 A 20041224; JP 2004019317 W 20041224; JP 2005517389 A 20041224; KR 20067012794 A 20060626; TW 93140573 A 20041224; US 58289704 A 20041224